

B2
~~urging the first substrate and the electronic device towards one another so that the flexible contact elements make contact with the electronic component.~~

Sub B3
30. ~~(Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer.~~

A1
31. (Added) A method according to claim 30, wherein the area is a plurality of integrated circuits on the semiconductor wafer; and the flexible contacts make contact with the plurality of die sites all at once.

Sub B4
32. ~~(Added) A method according to claim 29, wherein the area of the electronic device is a portion of an overall surface area of the electronic device.~~

Sub B5
33. ~~(Added) A method according to claim 29, wherein the electronic device is a printed circuit board.~~

Sub B6
34. ~~(Added) A method according to claim 29, wherein the electronic device is a packaging substrate.~~

35. (Added) A method according to claim 29, wherein the flexible elements are probe elements.

Sub B7
36. ~~(Added) A method according to claim 29, wherein the flexible elements further includes a protuberance at an end thereof.~~

Sub B8
37. ~~(Added) A method according to claim 29, wherein the flexible elements are shaped wires disposed on the surface of the second substrate.~~

Sub
B9
38. (Added) A method according to claim 29, wherein there are electrical connections between the second substrates and the first substrate.

Sub
B10
39. (Added) A method according to claim 29, wherein the first substrate is a space transformer.

Sub
B11
40. (Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer; and the flexible contact elements of the second substrate contact individual semiconductor dies on the semiconductor wafer.

Sub
B12
41. (Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer; and the flexible contact elements of the second substrate contacts at least one integrated circuit on the semiconductor wafer.

Sub
B13
42. (Added) A method according to claim 29, wherein the second substrate is aligned to the large substrate by a socket.

Sub
B14
43. (Added) A method according to claim 29, wherein the first substrate with the second mounted thereto is mounted to an electrical testing apparatus.

Sub
B15
44. (Added) A method according to claim 29, wherein the first substrate with the second mounted thereto is mounted to an electrical testing apparatus by a plurality of electrical connections.

Sub
B16
45. (Added) A probe card assembly comprising:

a probe card;

B16
a plurality of probe elements;

AA
a space transformer substrate having a top surface, a bottom surface, a first plurality of terminals disposed on the top surface, and a second plurality of terminals disposed on the bottom surface;

at least one second substrate having a top surface, a bottom surface;

means for effecting electrical connections between the at least one second substrate and the space transformer substrate; and

a plurality of probe elements disposed on the top surface of the at least one first substrate.

46. (Added) A probe card assembly, according to claim 45, wherein the probe elements are free-standing flexible conductors.

Sub B17
47. (Added) A probe card assembly, according to claim 46, wherein tip structures mounted to ends of the plurality of free-standing flexible conductors.

Sub B18
48. (Added) A probe card assembly, according to claim 46, characterized in that: the free-standing flexible conductor further indicates a protuberance at an end thereof.

Sub B19
49. (Added) A first substrate adapted in use to be mounted as a substrate tiles to a second substrate, comprising:

the first substrate having two opposite surfaces;

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~~flexible contacts extending from one of the two surfaces;~~

~~terminals on an other of the two opposite surfaces; and~~

~~means, within the first substrate, for connecting the terminals to the contacts.~~

~~320 A~~
50. (Added) A method according to claim 29, further including plurality of groups of said plurality of the flexible electrical contact elements.

Sub B21
~~51. (Added) A method according to claim 29 or 49, wherein there is a least one of said second substrates mounted to said first substrate.~~

Sub B22
52. (Added) A method according to claim (27 to 28 or 49) wherein there are a plurality of said second substrates mounted to said first substrate.

REMARKS

Support for the added claims is found throughout the specification, in particular in US Patent 5,371,654, col. 6, lines 39-57, which patent is incorporated by references as US Application Serial Number 07/963,364 on page 8. Also, Fig. 3 shows an example of an embodiment where substrate 54 is electrically coupled to substrate 68 by interposer 76. A